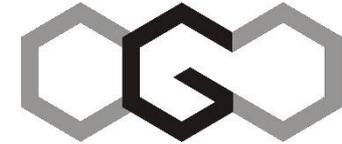




UNIVERSITY OF
CAMBRIDGE
Department of Engineering



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GRAPHENE
CENTRE

Graphene electronics and optoelectronics

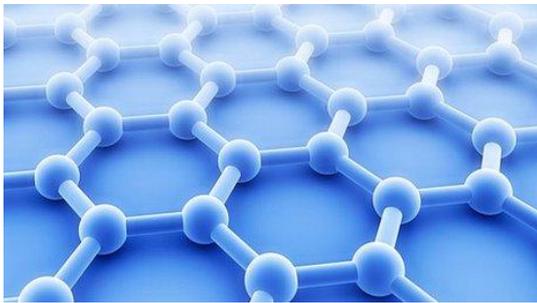
Antonio Lombardo

11 June 2014

al515@cam.ac.uk

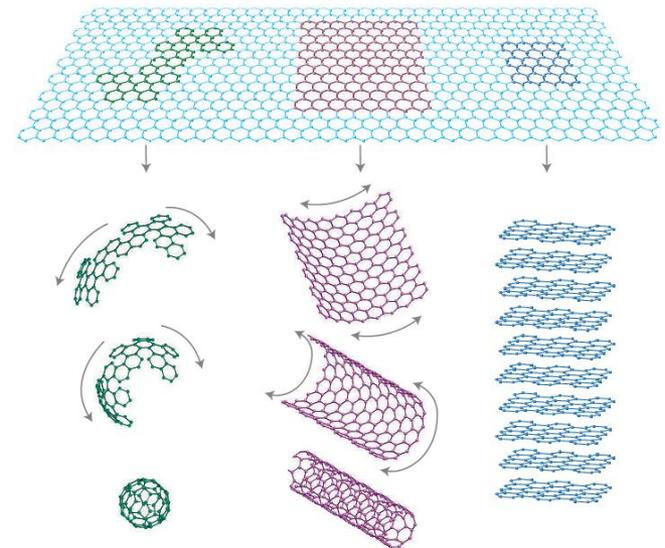
Graphene: what is that?

“Sheet” of carbon atoms arranged in an hexagonal lattice, one atom thick!



“Building block” for carbons of other dimensionalities:

- graphite
- carbon nanotubes
- fullerenes



Nature Materials 6, 183

Graphene: the groundbreaking experiment

22 OCTOBER 2004 VOL 306 SCIENCE

Electric Field Effect in Atomically Thin Carbon Films

K. S. Novoselov,¹ A. K. Geim,^{1*} S. V. Morozov,² D. Jiang,¹
Y. Zhang,¹ S. V. Dubonos,² I. V. Grigorieva,¹ A. A. Firsov²



Individual graphene layers can be extracted from 3-dimensional graphite

Stable under ambient conditions

Remarkable electronic properties: ambipolar transport, mobility $\sim 10^3$ cm²/Vs



Nobel prize in
Physics 2010

Graphene: properties & technology

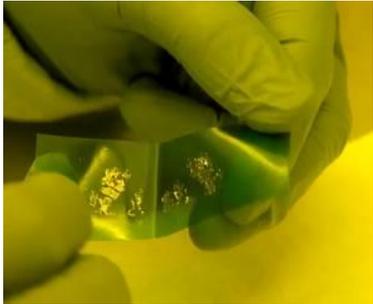
Properties:

- Charge carriers mobility: $>10^5$ cm²/Vs (room T), $>10^6$ cm²/Vs (low T) – high speed
- Saturation velocity: $> 10^7$ cm/s (even for fields up to 50 KV/cm) – scalability
- Thermal conductivity: $> 3,000$ WmK⁻¹ – heat dissipation
- Current-carrying capacity: $>10^8$ A/cm² - interconnects
- Young modulus ~ 1 TPa
- Stretchable up to 20% - flexible, wearable electronics
- Broadband optical absorption - optoelectronics
- Possibility of chemical functionalization

Technology:

- fully compatible with silicon-based planar fabrication technology
- can be integrated with practically every substrate (e.g. Si, plastic, etc.)

Graphene: production



Mechanical cleavage

- Highest quality
- Low yield



- Research
- Prototyping

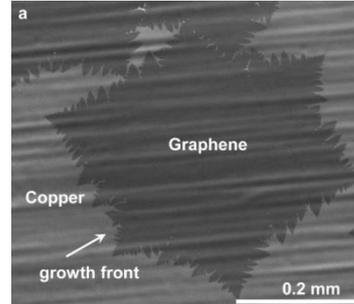


Liquid phase exfoliation

- Exfoliation by ultrasounds
- Cheap and scalable



- Inks, printed electronics
- Coatings
- Composites

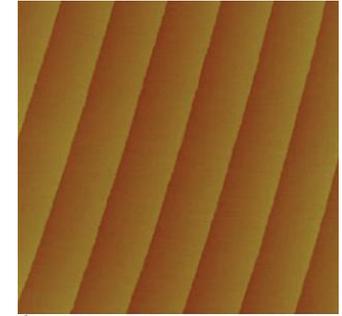


Chemical vapour deposition

- Growth on Cu, scalable
- Transfer



- Large area
- Integrated circuits



Growth on SiC

- Thermal decomposition
- High T

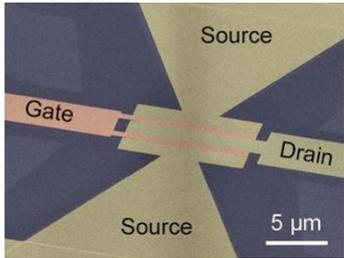


- High-frequency electronics

Graphene: a “family” of materials, very different properties

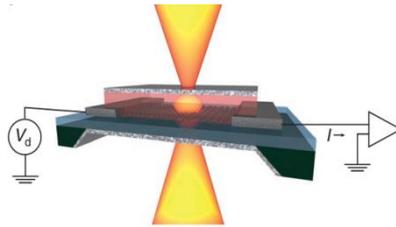
Graphene production and processing review: Bonaccorso, Lombardo et al., Materials Today 15, 564

Graphene: applications



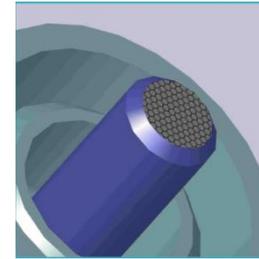
Electronics:

- High-frequency transistors
- Printed electronics



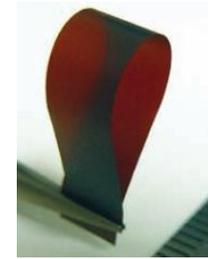
Optoelectronics

- Photodetectors
- THz detectors



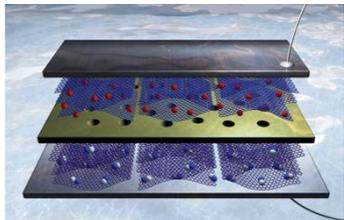
Photonics

- Optical modulators
- Mode-locked lasers



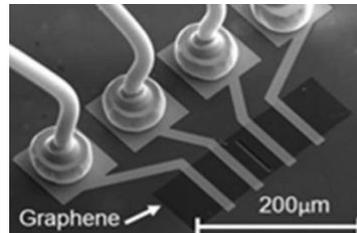
Composites & coatings

- Reinforcements
- Barriers



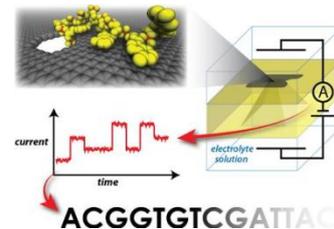
Energy:

- Supercapacitors
- Batteries



Sensors & metrology:

- Strain gauges
- Resistance standards (QHE)



Bioapplications:

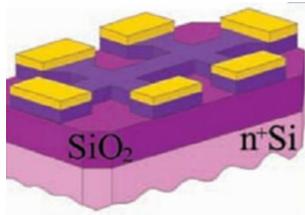
- Drug delivery
- Support for TEM
- Biosensing (e.g. DNA)



“Graphene does not just have one application, It is not even one material. It is a huge range of materials. A good comparison would be to how plastics are used”

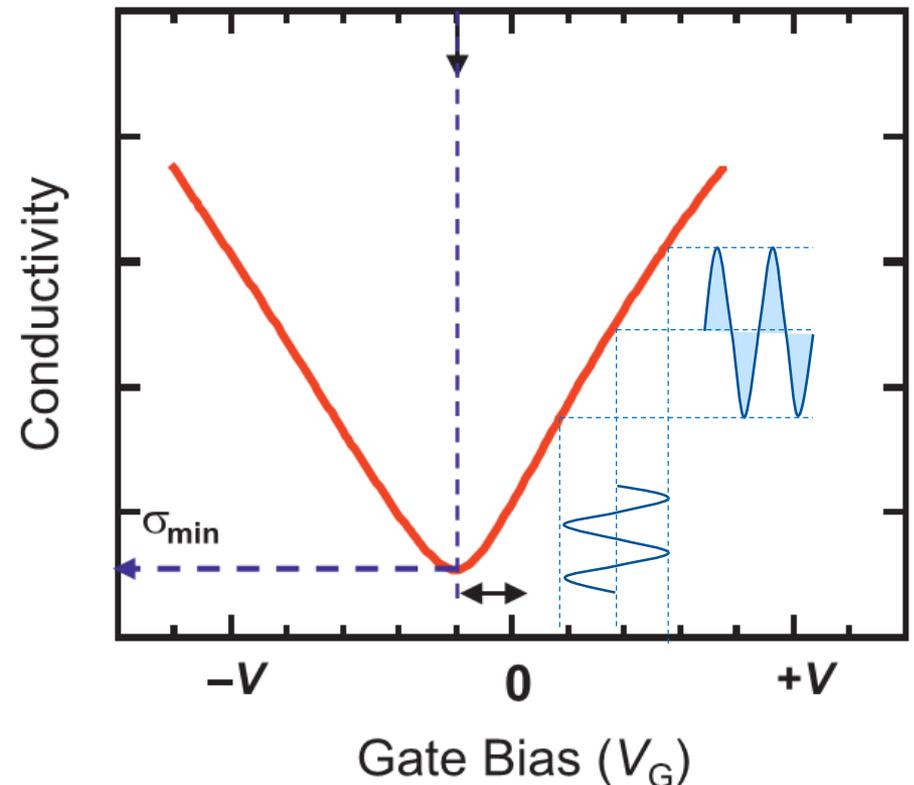
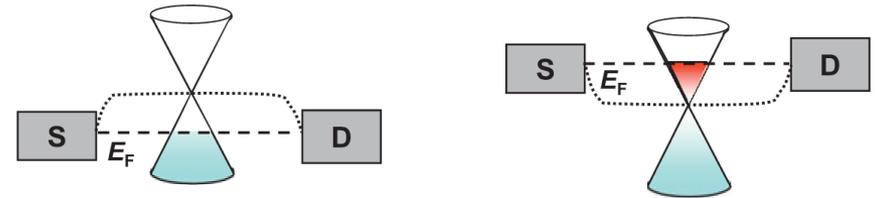
BBC News, May 2011

Graphene field effect transistors (GFETs)



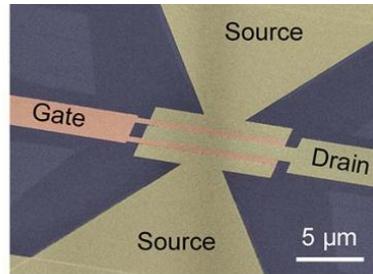
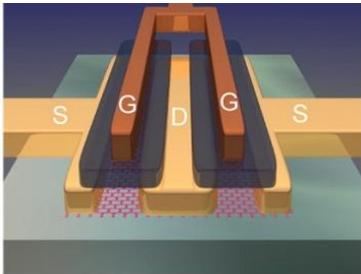
[Novoselov et al., Science 306]

- Back gating (heavily doped Si substrate): optical visibility, easy fabrication
- **Ambipolar** field effect: charge carriers can be continuously “tuned” between electron and holes.
- Graphene FETs do not switch off completely, $I_{ON/OFF}$ ratio ~ 10
- In **analog RF**, switch off not essential (e.g. signal amplifiers always ON state)

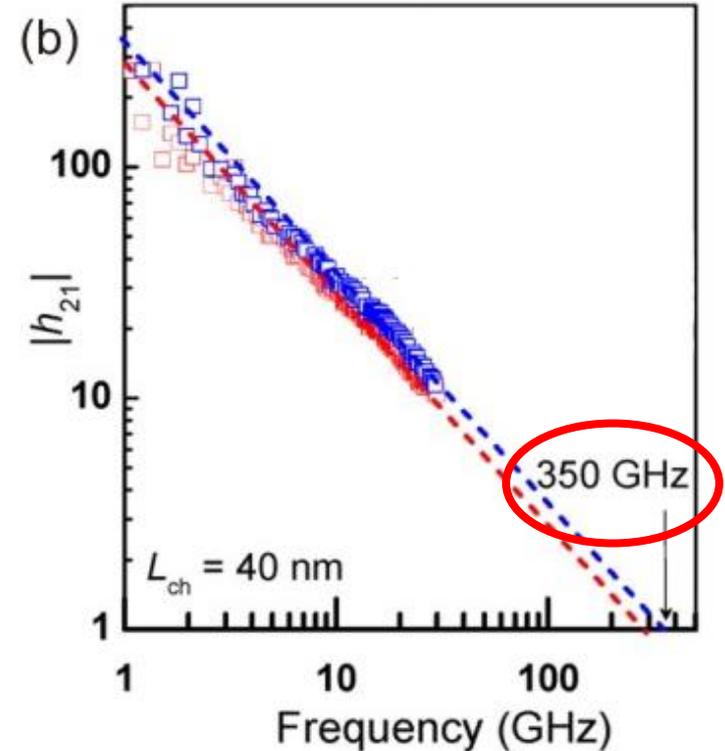
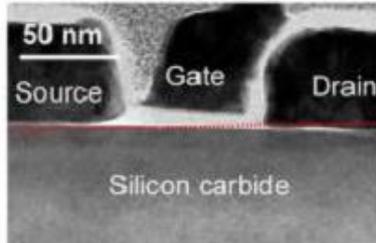
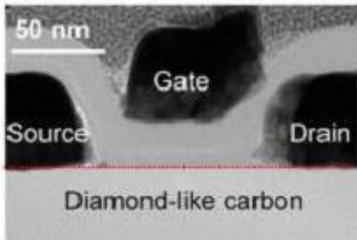


Graphene RF transistors

- Robustness against short channel effect
- High saturation velocity ($>3 \times 10^7$ cm/s) even at high field
- Dual channel configuration



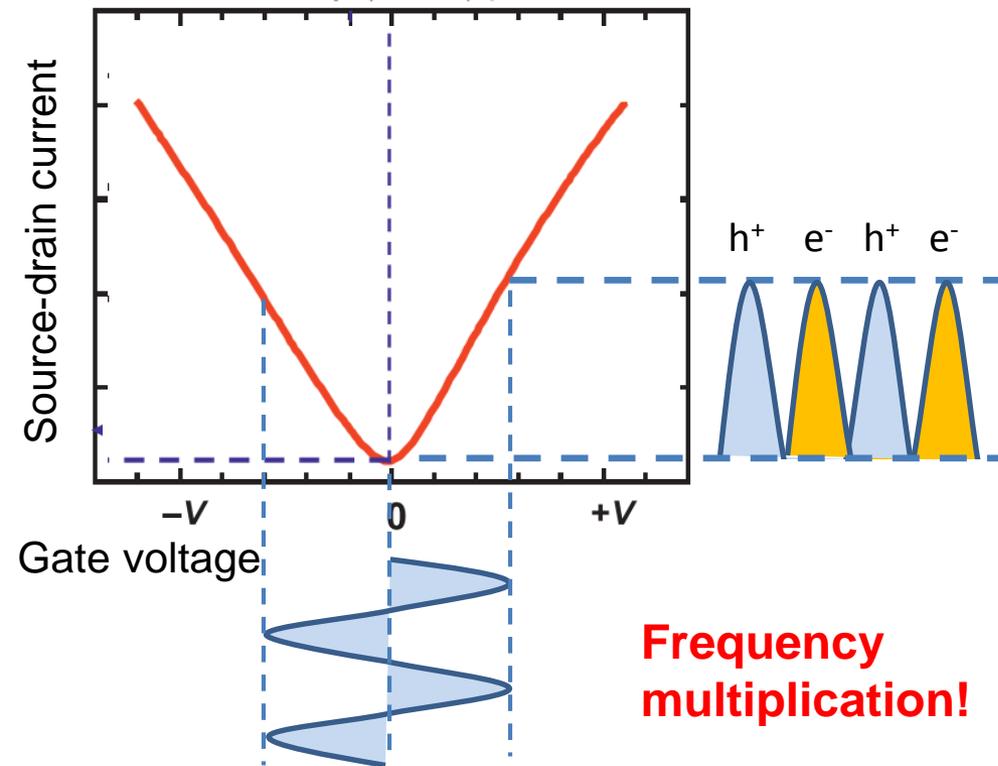
- Already scalable, operating frequencies above 300GHz both on CVD and epitaxial graphene



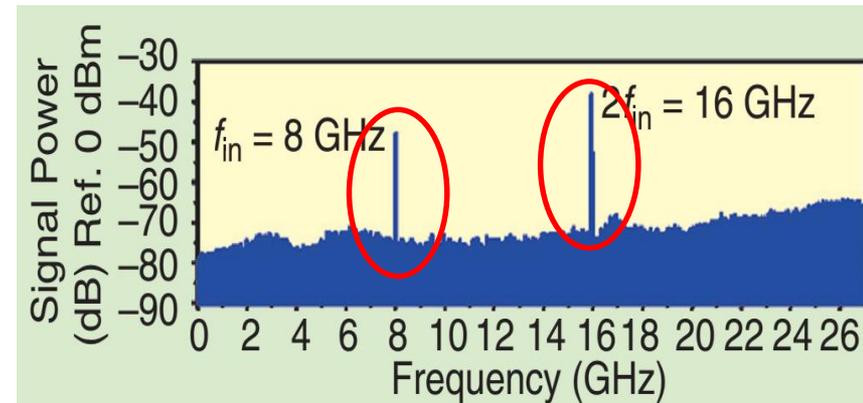
[Wu et al., Nano Lett. 12, 3062]

GFETs as frequency multipliers

- Ambipolar field effect, symmetric transfer characteristics



Frequency multiplication!



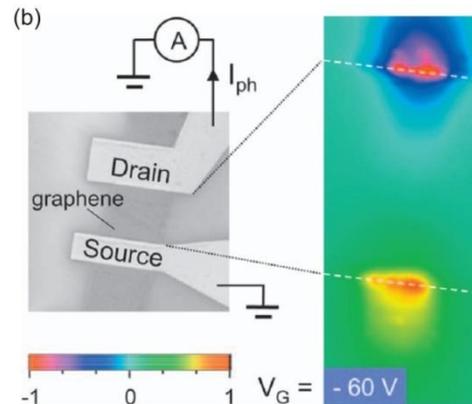
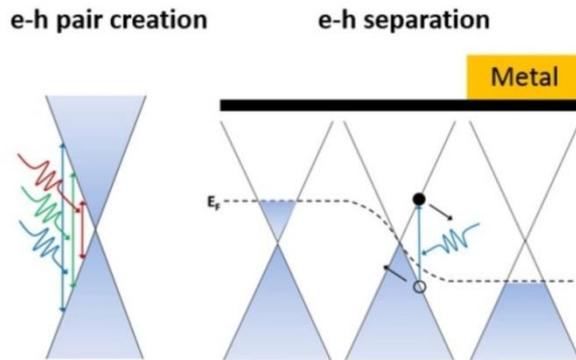
Peak @16GHz = 11dB higher than peak @8GHz \rightarrow 93% of the output power is at the doubled frequency

Single transistor, no filtering element!

[Wang et al., IEEE Microw. Mag. 13]

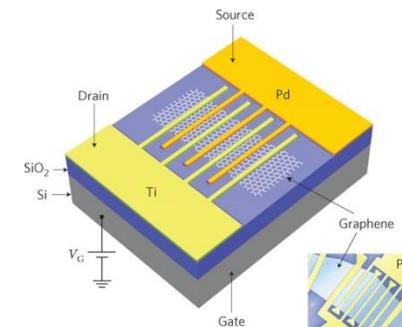
Graphene photodetectors

- Strong interaction with light (2.3% absorption)
- Broadband absorption
- Working principle: internal fields occurring at metal-graphene interface



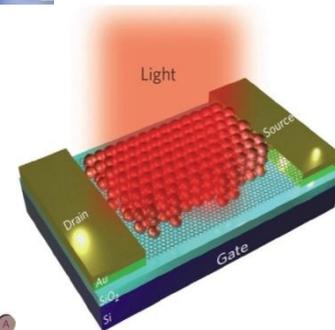
[Mueller et al., PRB 79, 245430]

- Improvement of responsivity

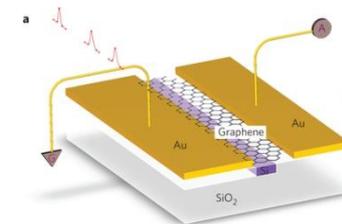


Mueller et al.
Nature Photonics 4,
297

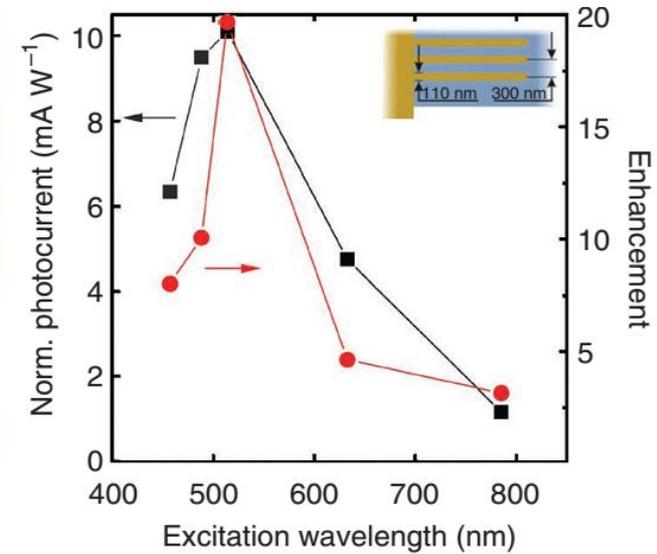
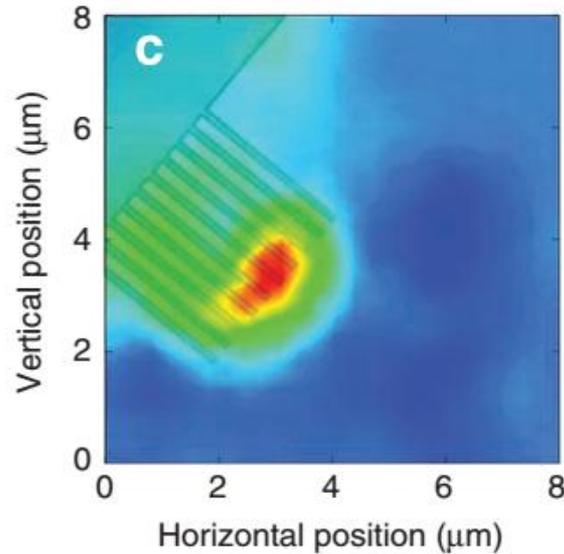
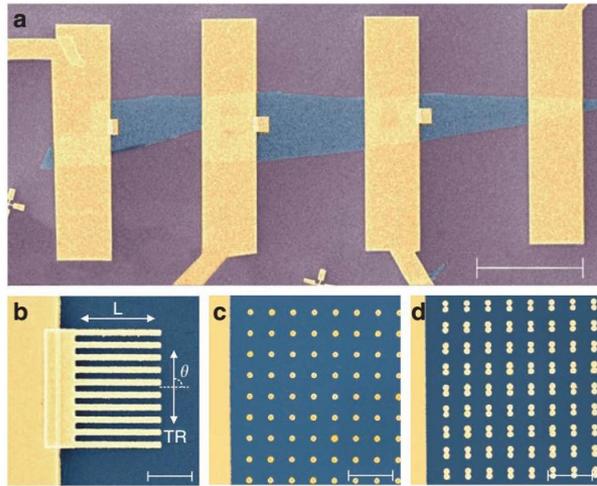
Konstantatos, et al.
Nature Nanotech. 7,
363



Gan, et al.
Nature Photonics
7, 883



Plasmonic-enhanced photodetectors

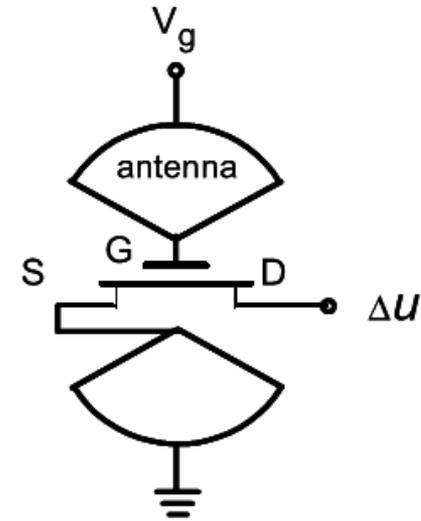


- Combination of graphene with plasmonic nanostructures
- Wavelength and polarization selectivity

[Echtermeyer, Britnell, Jasnos, Lombardo et al., Nature Comm. 2, 458]

FET as THz detectors

- FET (Dyakanov-Shur) detection mediated by generation of **plasma waves** in the channel → high sensitivity, fast response
- THz radiation coupled between **gate** and **source** (antenna coupling)
- THz field induces **plasma waves** propagating in the FET channel
- **Resonant** detection: only at specific radiation frequency
- **Non resonant** detection (plasma waves overdamped): broadband
- Modulation of both **charge carrier density** and **carrier drift velocity**.
- Carriers travelling towards the drain generates a **DC voltage** between source and drain

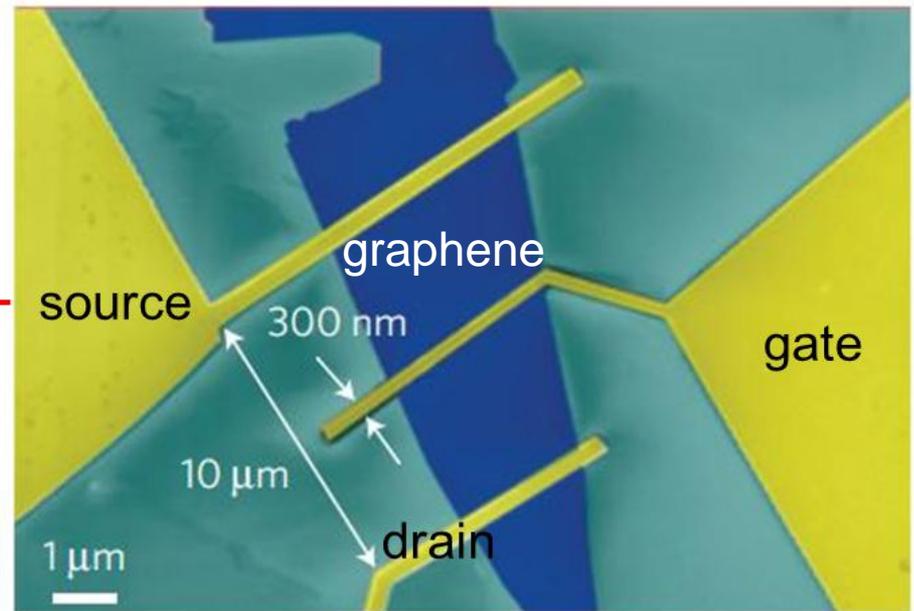
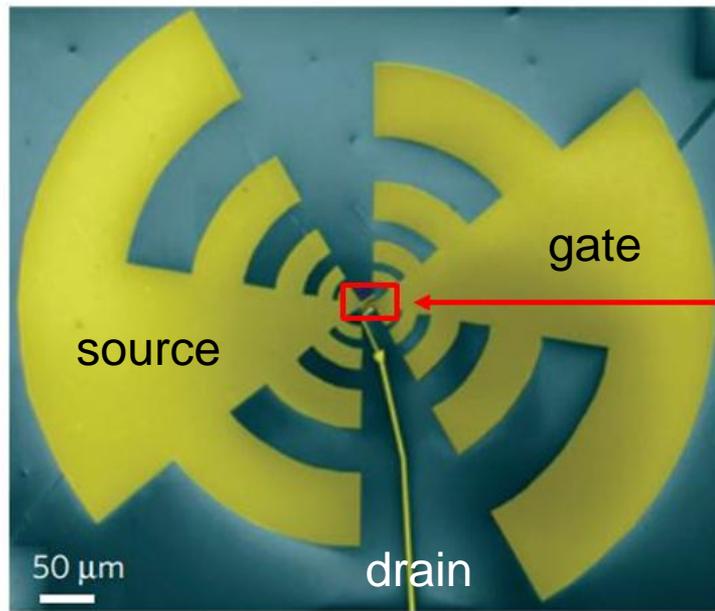


[Knap et al., Nanotech. 24]

- Key requirement: **high mobility** → **graphene** – **AT ROOM TEMPERATURE**
- Graphene supports **plasma waves** weakly damped

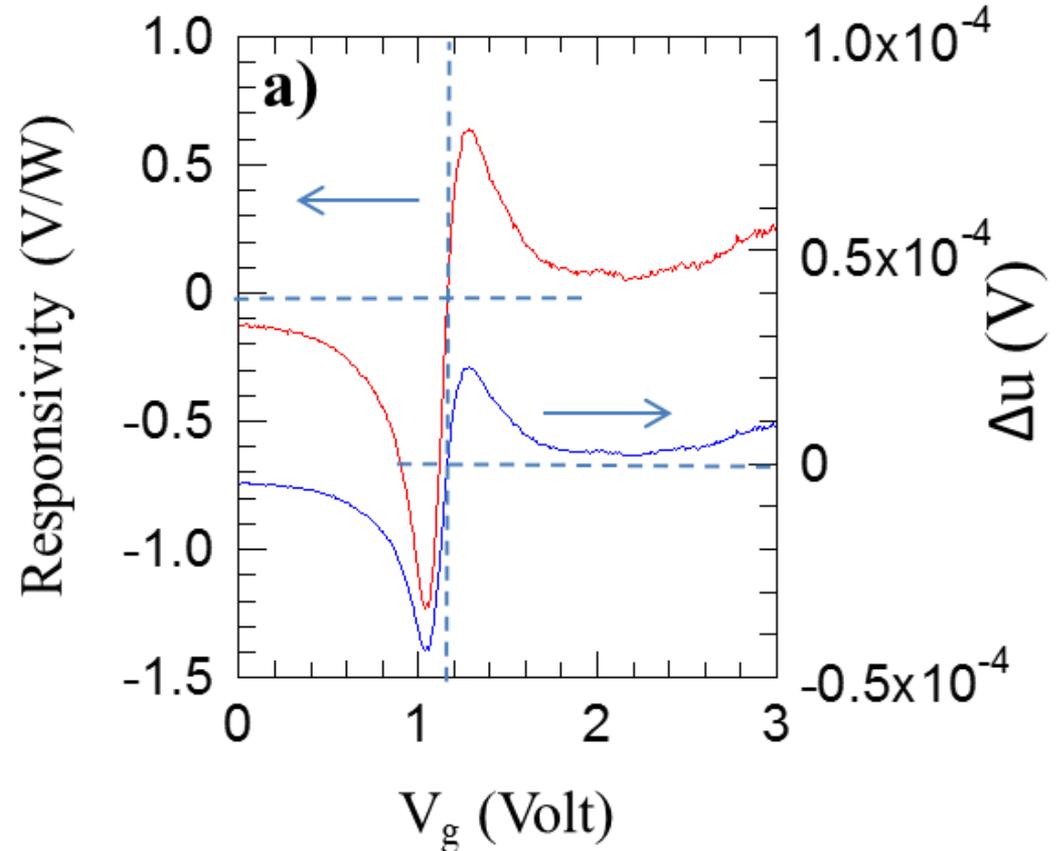
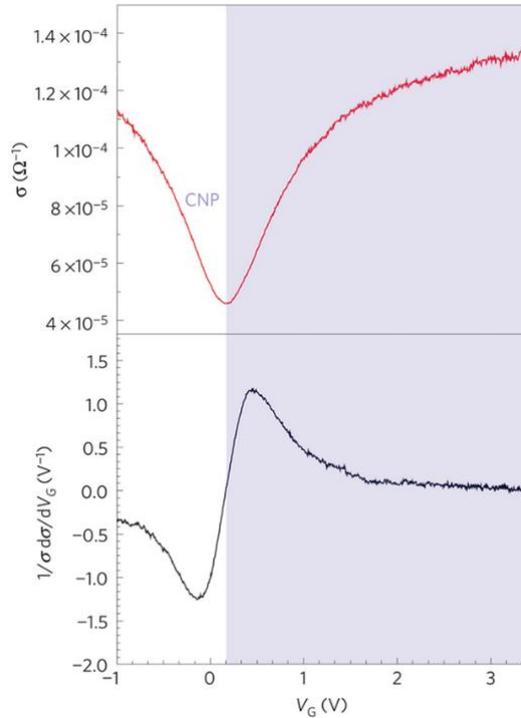
Graphene FET as THz detectors

- Graphene on high-resistivity silicon
- Source (antenna lobe); drain “standard” contact
- ALD deposition of HfO₂
- Gate (antenna lobe) fabrication



[Vicarelli, Vitiello, Coquillat, Lombardo et al., Nature Materials 11]

Graphene FET as THz detectors

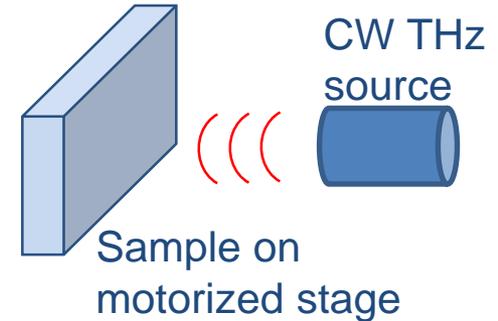
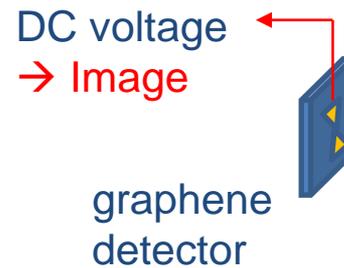


- Max responsivity $> 1\text{V/W}$
- Noise equivalent power (NEP) $\sim 2 \times 10^{-9} \text{ W/Hz}^{1/2}$

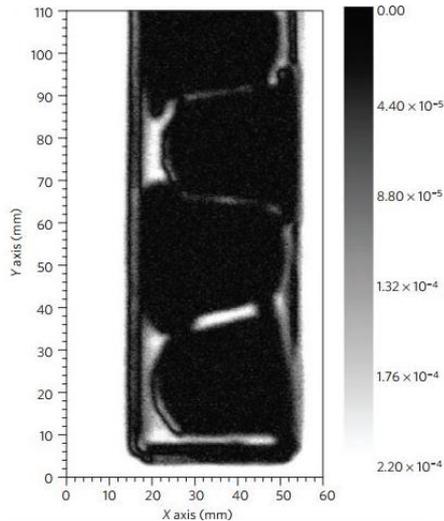
[Vicarelli, Vitiello, Coquillat, Lombardo et al., Nature Materials 11] [Spirito, Coquillat, De Bonis, Lombardo et al., Appl.Phys. Lett. 104]

THz imaging using graphene detectors

- Transmission image
- Focalized THz, spot size $\sim 1\text{mm}$
- Sample on motorized stage
- Integration time **20ms**



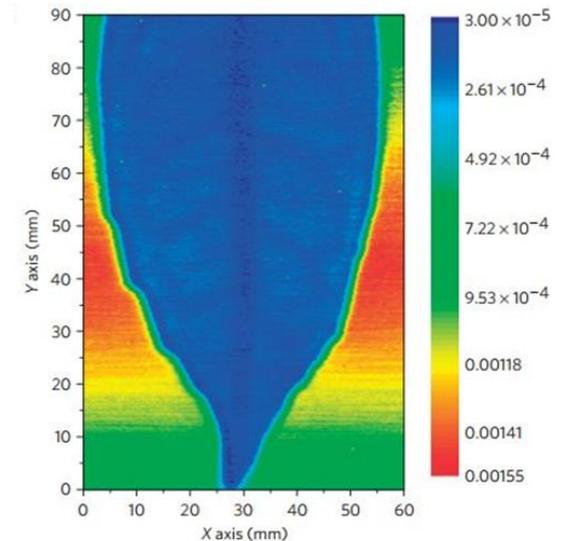
Cardboard box
(closed)



THz image



Open
box



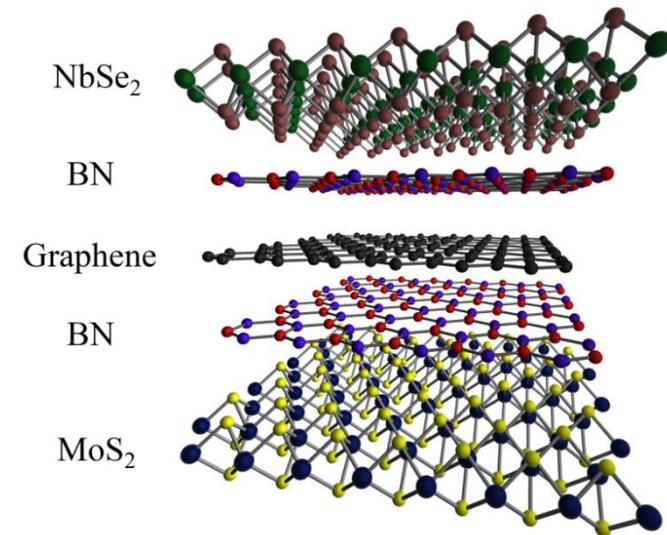
Fresh leaf

[Vicarelli, Vitiello, Coquillat, Lombardo et al., Nature Materials 11]

Beyond graphene: layered materials

Layered materials: solids with strong in-plane chemical bonds but weak out-of-plane Van der Waals bonds.

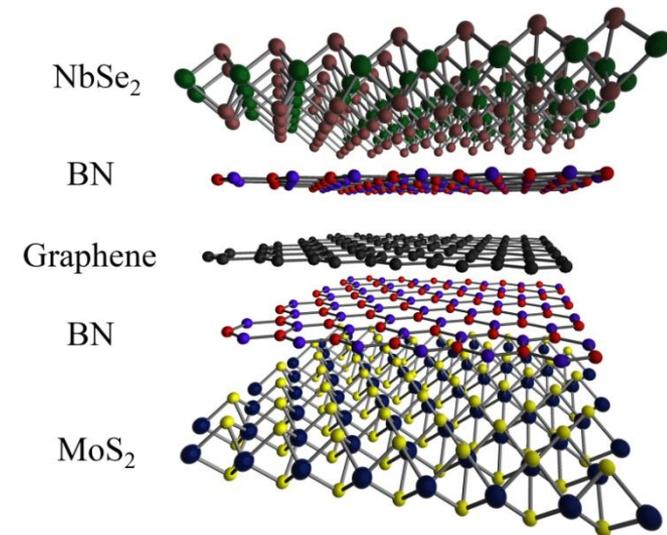
- Hexagonal boron nitride (h-BN)
- Transition metal dichalcogenides (TMDC): MoS_2 , WSe_2 , ...
- Transition metal trichalcogenides (TMTc): TiS_3 , TaSe_3 , ...
- Metal halides: PbI_2 , MgBr_2 , ...
- Metal oxides: MnO_2 , LaNb_2O_7 , ...
- III-VI semiconductors: GaS , InSe , ...
- Double hydroxides (LDHs):
- Clays (layered silicates)
- ...



Beyond graphene: layered materials

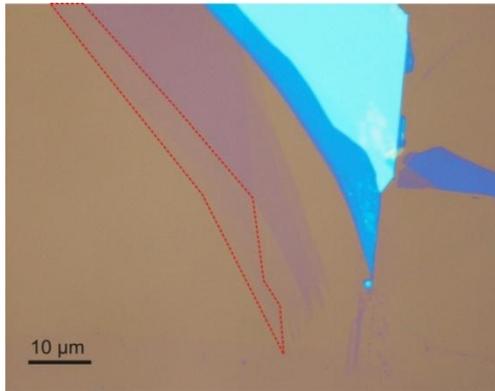
Layered materials: solids with strong in-plane chemical bonds but weak out-of-plane Van der Waals bonds.

- Hexagonal boron nitride (h-BN)
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- Double hydroxides (LDHs):
- Clays (layered silicates)
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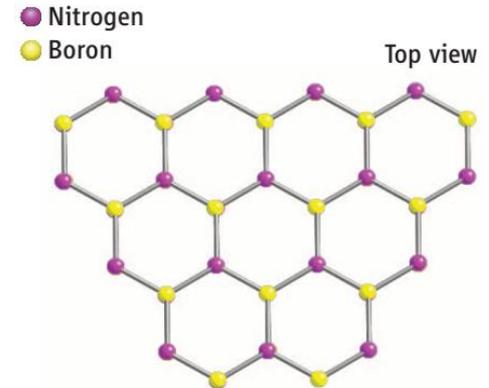


Hexagonal boron nitride

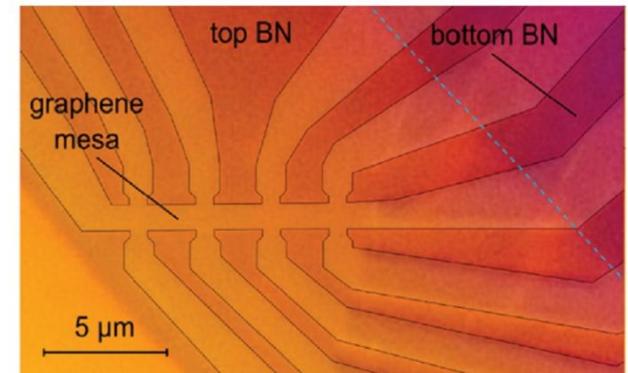
- Isomorph of graphite
- Insulator, bandgap: 5.97 eV
- Dielectric constant ~ 3.9 , breakdown field $\sim 0.7\text{V}/\text{nm}^{-1}$
- Inert, free of dangling bonds and surface charge traps



- Support and/or encapsulate graphene: room-temperature, micrometric scale ballistic transport, mobility $> 10^5 \text{ cm}^2/\text{Vs}$



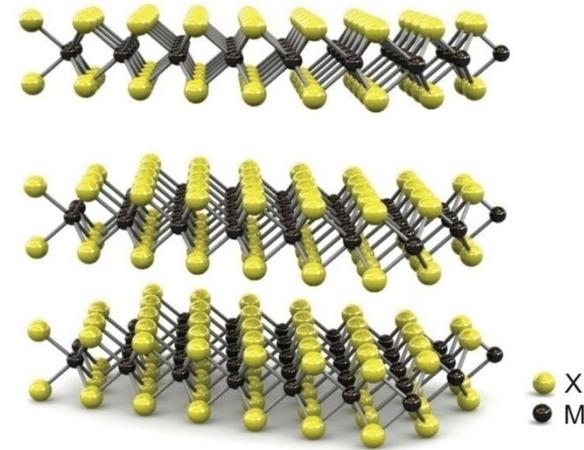
[Nicolosi et al., Science 340, 1420]



[Mayorov et al., Nano Lett. 11, 2396]

Transition metal dichalcogenides

- Compound formed by a transition metal element (M) and a chalcogen (X), generalized formula MX_2
- Layered structure, planes of the form XMx coupled by Van der Waals forces
- Very different electronic properties: insulators (HfS_2), semiconductors (e.g. MoS_2), metals (NbS_2)
- Bandstructure changes significantly with the number of layers: MoX_2 and WX_2 indirect as bulk, direct (and larger) as single layer

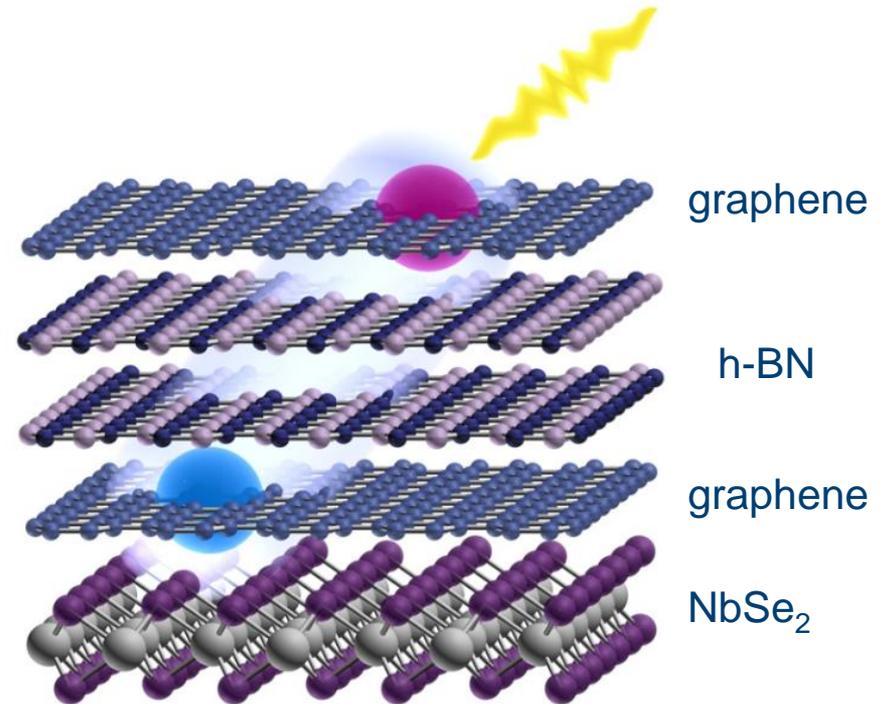


[Wang et al., Nature Nanotech. 7, 699]

Heterostructures

- Stacks of two-dimensional materials
- Not only combination of individual properties, but result of interaction between layers
- Tailored properties

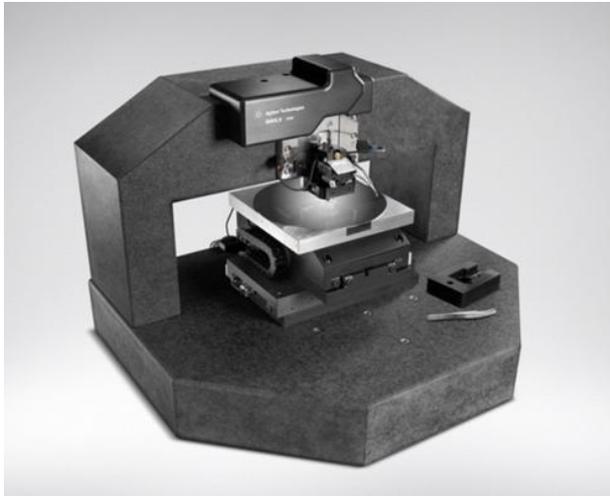
Materials “on demand”



[Novoselov et al., Phys. Scripta T146, 14006]

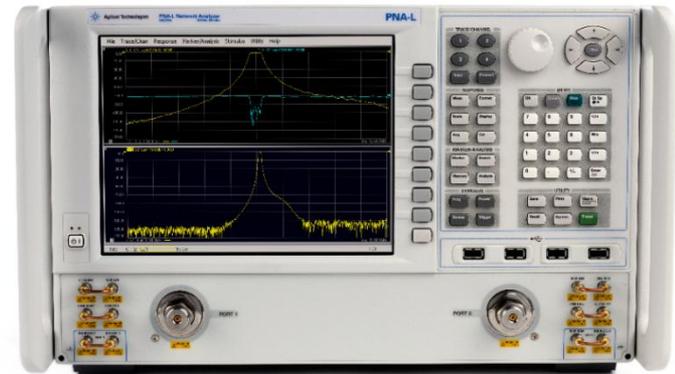
RF and microwave measurements at the nanoscale

- Spatially-resolved high-frequency measurements
- there is *still* room at the bottom: **scanning microwave microscopy**



Atomic Force Microscope (AFM)

High spatial resolution (nm)



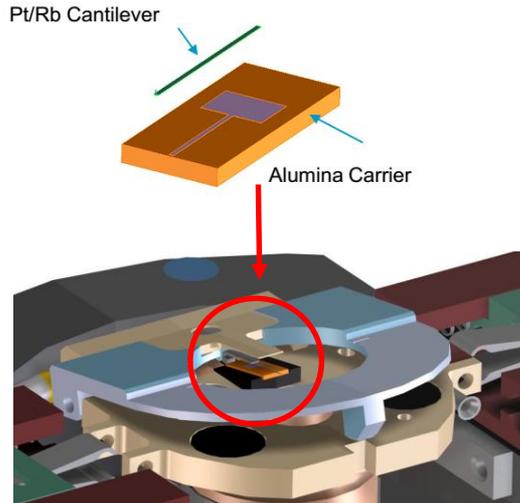
Vector Network Analyser (VNA)

Quantitative broadband measurement
at RF and microwave frequencies



Agilent Technologies

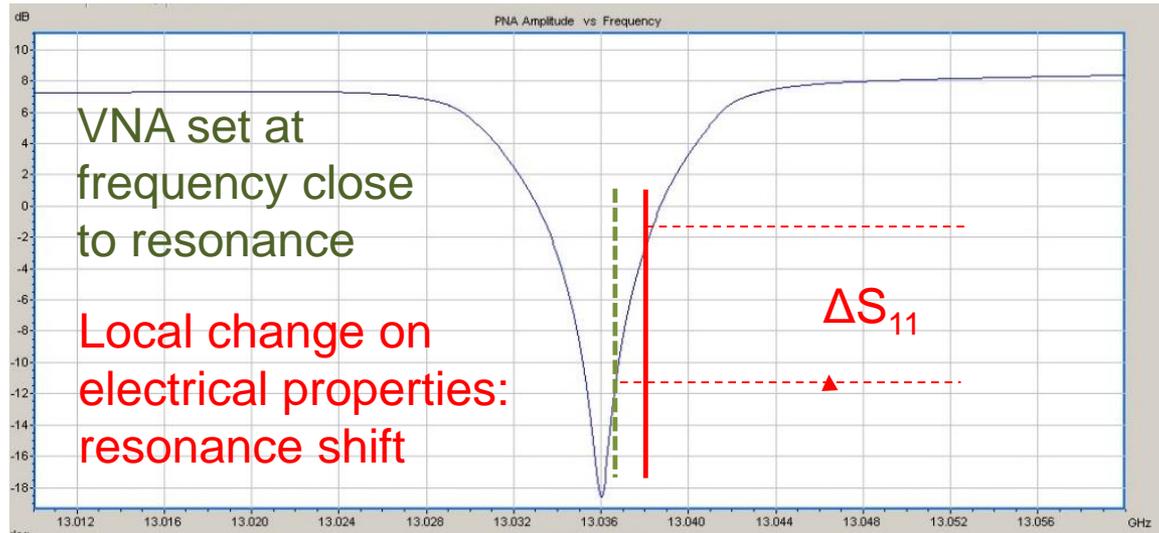
Scanning Microwave microscopy (SMM)



Metallic tip

Changes in S_{11} parameter
(reflected signal)

Tip+network: resonator



Conclusions

- Graphene exhibits unique combination of properties
- Graphene: “family” on materials, very different properties according to production method
- Applications: high frequency electronics and optoelectronics
- Not simple “replacement” for other materials, but novel material with specific properties (and also specific challenges)
- Two-dimensional materials, similar structure but very different properties
- Heterostructures, materials “on demand”
- Scanning microwave microscopy: investigation of high-frequency properties at the nanoscale

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